

CLAIMS

1. A thermal trip device in which a bimetal is heated by overcurrent and performs trip operation of a circuit by curvature of said heated bimetal,

5 wherein at least one part of the surface of said bimetal is made to be black.

2. The thermal trip device according to claim 1, wherein at least one part of the surface of said bimetal is made to be matte black.

10 3. The thermal trip device according to claim 1, wherein the surface of a temperature measurement part of said bimetal is made to be black.

4. The thermal trip device according to claim 3, wherein the surface of said temperature
15 measurement part of said bimetal is made to be matte black.

5. The thermal trip device according to claim 3, wherein said temperature measurement part of said bimetal is provided with a bending part bent
20 substantially perpendicular to longitudinal direction, and the surface of said bending part is made to be black.

6. The thermal trip device according to claim 4, wherein said temperature measurement part of said
25 bimetal is provided with a bending part bent substantially perpendicular to longitudinal direction, and the surface of said bending part is made to be

matte black.

7. A thermal trip device in which a bimetal is heated by overcurrent and performs trip operation of a circuit by curvature of said heated bimetal,

5 wherein a temperature measurement part of said bimetal is provided with a bending part bent substantially perpendicular to longitudinal direction.

8. A circuit breaker having a thermal trip device in which a bimetal is heated by overcurrent and
10 performs trip operation of a circuit by curvature of said heated bimetal,

 wherein the surface of a temperature measurement part of said bimetal is made to be black.

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